







住址: 407 台中市中清路 163 號 No. 163 Chung Ching RD., Taichune, Taiwan, R.O.C

WEB: <u>http://www.winstar.com.tw</u> E-mail: sales@winstar.com.tw Tel:886-4-24262208 Fax : 886-4-24262207

SPECIFICATION

CUSTOMER :

MODULE NO.: WH1602B-YYC-JT#000

APPROVED BY:

(FOR CUSTOMER USE ONLY)

PCB VERSION:

DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
	第 1 頁	〔,共 29 頁	WS-EP-008 10(A)

VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2009/5/5		First issue

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VERSION	DATE	REVISED PAGE NO.			
0	2009/5/5		Fi	rst issue	

Contents

1.Module Classification Information

2.Precautions in use of LCD Modules

3.General Specification

4. Absolute Maximum Ratings

5.Electrical Characteristics

6.Optical Characteristics

7.Interface Pin Function

8. Contour Drawing & Block Diagram

9. Function Description

10. Character Generator ROM Pattern

11.Instruction Table

12. Timing Characteristics

13.Initializing of LCM

14.Reliability

15.Backlight Information

16. Inspection specification

17. Material List of Components for RoHs

<u>1.Module Classification Information</u>

	$\frac{B}{\sqrt{Y}} - \frac{YYC}{\sqrt{y}} - \frac{JT\#000}{er}$	
M Brand : WINSTAR	DISPLAY CORPORATION	
7	Character Type, G→Graphic T	vpe
	racter 16 words, 2Lines.	
\checkmark Model serials no.		
𝕉 Backlight Type∶	N→Without backlight	$T \rightarrow LED$, White
	$B \rightarrow EL$, Blue green	$A \rightarrow LED$, Amber
	D→EL, Green	$R \rightarrow LED$, Red
	$W \rightarrow EL$, White	$O \rightarrow LED$, Orange
	$F \rightarrow CCFL$, White	$G \rightarrow LED$, Green
	$Y \rightarrow LED$, Yellow Green	
🗯 LCD Mode :	$B \rightarrow TN$ Positive, Gray	$T \rightarrow FSTN$ Negative
	N→TN Negative,	
	G→STN Positive, Gray	
	$Y \rightarrow STN$ Positive, Yellow Gre	en
	M→STN Negative, Blue	
	$F \rightarrow FSTN$ Positive	
H LCD Polarize	$A \rightarrow Reflective, N.T, 6:00$	$H \rightarrow$ Transflective, W.T,6:00
Type/ Temperature	$D \rightarrow Reflective, N.T, 12:00$	$K \rightarrow$ Transflective, W.T,12:00
range/ View direction	$G \rightarrow Reflective, W. T, 6:00$	C→Transmissive, N.T,6:00
direction	J→Reflective, W. T, 12:00	$F \rightarrow$ Transmissive, N.T,12:00
	$B \rightarrow Transflective, N.T, 6:00$	$I \rightarrow$ Transmissive, W. T, 6:00
	$E \rightarrow Transflective, N.T.12:00$	L→Transmissive, W.T,12:00
er Special Code	JT : English and Japanese stan #:Fit in with the ROHS Direct 00-Sales code	
	0: Version (Assigned FRNorr	nal Temperature LCDAll the materials in
	BOM are assigned.)	

2 Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.

<u>3</u> .General Specification

Item	Dimension	Unit			
Number of Characters	16 characters x 2 Lines	—			
Module dimension	80.0 x 36.0 x 13.2(MAX)	mm			
View area	66.0 x 16.0	mm			
Active area	56.2 x 11.5	mm			
Dot size	0.55 x 0.65	mm			
Dot pitch	0.60 x 0.70	mm			
Character size	2.95 x 5.55	mm			
Character pitch	3.55 x 5.95	mm			
LCD type	STN Positive, Yellow Green Transmissive (In LCD production, It will occur slightly colo can only guarantee the same color in the same				
Duty	1/16				
View direction	6 o'clock				
Backlight Type	LED Yellow Green				

<u>4</u> .Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T _{OP}	-10		+60	°C
Storage Temperature	T _{ST}	-20		+70	°C
Input Voltage	VI	V _{SS}		V _{DD}	V
Supply Voltage For Logic	V _{DD} -V _{SS}	-0.3	_	7	V
Supply Voltage For LCD	V_{DD} - V_0	-0.3		13	V

5 .Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V _{DD} -V _{SS}	_	4.5	5.0	5.5	V
Supply Voltage For		Ta=-10°C	—	_	5.2	V
LCD	V_{DD} - V_0	Ta=25℃	—	3.7	—	V
*Note		Ta=60°C	3.2	_	_	V
Input High Volt.	V _{IH}	_	0.7 V _{DD}	_	V _{DD}	V
Input Low Volt.	V _{IL}	_	V _{SS}	_	0.6	V
Output High Volt.	V _{OH}	—	3.9		—	V
Output Low Volt.	V _{OL}	_	—	—	0.4	V
Supply Current	I_{DD}	V _{DD} =5.0V	1.0	1.2	1.5	mA

* Note: Please design the VOP adjustment circuit on customer's main board



<u>6</u> .Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V) θ	СКЊ2	20		40	deg
	(H) φ	СКЊ2	-30		30	deg
Contrast Ratio	CR	_	_	3	_	_
Response Time	T rise	_		150	200	ms
	T fall	—	—	150	200	ms

Definition of Operation Voltage (Vop)





Definition of Response Time (Tr, Tf)



Conditions :

Operating Voltage : Vop Frame Frequency : 64 HZ Viewing Angle(θ , φ): 0° , 0° Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CRb2)



7. Interface Pin Function

Pin No.	Symbol	Level	Description
1	V _{SS}	0V	Ground
2	V _{DD}	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read(MPU→Module) L: Write(MPU→Module)
6	Е	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	А	_	LED +
16	K		LED-

<u>8</u> .Contour Drawing & Block Diagram



第 10 頁,共 29 頁



<u>9</u> .Function Description

The LCD display Module is built in a LSI controller, the controller has two 8-bit registers, an instruction register (IR) and a data register (DR).

The IR stores instruction codes, such as display clear and cursor shift, and address information for display data RAM (DDRAM) and character generator (CGRAM). The IR can only be written from the MPU. The DR temporarily stores data to be written or read from DDRAM or CGRAM. When address information is written into the IR, then data is stored into the DR from DDRAM or CGRAM. By the register selector (RS) signal, these two registers can be selected.

RS	R/W	Operation
0	0	IR write as an internal operation (display clear, etc.)
0	1	Read busy flag (DB7) and address counter (DB0 to DB7)
1	0	Write data to DDRAM or CGRAM (DR to DDRAM or CGRAM)
1	1	Read data from DDRAM or CGRAM (DDRAM or CGRAM to DR)

Busy Flag (BF)

When the busy flag is 1, the controller LSI is in the internal operation mode, and the next instruction will not be accepted. When RS=0 and R/W=1, the busy flag is output to DB7. The next instruction must be written after ensuring that the busy flag is 0.

Address Counter (AC)

The address counter (AC) assigns addresses to both DDRAM and CGRAM

Display Data RAM (DDRAM)

This DDRAM is used to store the display data represented in 8-bit character codes. Its extended capacity is 80×8 bits or 80 characters. Below figure is the relationships between DDRAM addresses and positions on the liquid crystal display.



Display position DDRAM address

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
0	0	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F
40	0	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F

²⁻Line by 16-Character Display

Character Generator ROM (CGROM)

The CGROM generate 5×8 dot or 5×10 dot character patterns from 8-bit character codes. See Table 2.

Character Generator RAM (CGRAM)

In CGRAM, the user can rewrite character by program. For 5×8 dots, eight character patterns can be written, and for 5×10 dots, four character patterns can be written.

Write into DDRAM the character code at the addresses shown as the left column of table 1. To show the character patterns stored in CGRAM.

Relationship between CGRAM Addresses, Character Codes (DDRAM) and Character patterns

Table 1.

Character Codes (DDRAM data)	CGRAM Address	Character Patterns (CGRAM data)	
7 6 5 4 3 2 1 0	5 4 3 2 1 0	7 6 5 4 3 2 1 0	
High Low	High Low	High Low	
0 0 0 0 * 0 0 0	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	* * * 0 * * * 0 0 * * * 0 0 * * * 0 0 * * * 0 0 * * * 0 0 * * * 0 0 * * * 0 0 * * * 0 0 * * * 0 0 * * * 0 0 * * * 0 0	Character pattern(1) Cursor patter
0 0 0 0 * 0 0 1	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	* * * 0 0 0 * * * 0 0 0 0 * * * 0 0 0 0 * * * 0 0 0 0 * * * 0 0 0 0 * * * 0 0 0 0 * * * 0 0 0 0 * * * 0 0 0 0	Character pattern(2) Cursor patter
	$ \begin{array}{cccc} 0 & 0 & 0 \\ 0 & 0 & 1 \end{array} $	* * *	
			-
0 0 0 0 * 1 1 1	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	* * *	

For 5 * 8 dot character pattern

For 5 * 10 dot character patterns

Character Codes (DDRAM data)	CGRAM Address	Character Patterns (CGRAM data)
7 6 5 4 3 2 1 0	5 4 3 2 1 0	7 6 5 4 3 2 1 0
High Low	H ig h L o w	High Low
0 0 0 0 * 0 0 0	$\left(\begin{array}{cccccccccccccccccccccccccccccccccccc$	* * * 0 0 0 0 * * * 0 0 0 0 * * * 0 0 0 0 * * * 0 0 0 * * * 0 0 0 * * * 0 0 0 * * * 0 0 0 * * * 0 0 0 * * * 0 0 0 * * * 0 0 0 * * * 0 0 0 * * * 0 0 0 * * * 0 0 0
	1 0 1 0	* * * 0 0 0 0 0
		* * * * * * * *

C haracter pattern

Cursor pattern

🔳 : " High "

<u>10.</u> <u>.Character Generator ROM Pattern</u>

Table.2

Upper																
4 bit Lower 4 bit	LLLL	LLLH	LLHL	LLHH	LHLL	LHLH	LHHL	LННН	HLLL	HLLH	HLHL	HLHH	HHLL	HHLH	HHHL	нннн
LLLL	CG RAM (1)						•••									
LLLH	(2)							•==					.	÷;		
LLHL	(3)		::					•				•		.:: [:]		
LLHH	(4)						:	•							:2.	
LHLL	(5)										•••		.		I	5
LHLH	(6)											••••			1	
LHHL	(7)					<u>ار.</u>	 	۱					••••		Ē	
LННН	(8)		•	:			:	II								
HLLL	(1)		:]:::]			·=	•			. F	
HLLH	(2)					ار ا ا		:							- 1	
HLHL	(3)		:+:	8		·····	•	 								
нгнн	(4)			8											:-:	. 7=5
HHLL	(5)			•							÷	≞.;			:::-	FF
HHLH	(6)						ľ:						••••			÷
HHHL	(7)						•							••••	¦ [™] I	
нннн	(8)		.·· ^{··}	·			::	÷			:::	·	•••			

<u>11</u>. <u>Instruction Table</u>

Instruction				In	structi	ion Co	de				Description	Execution time	
mstruction	RS	R/W DB7		DB6	DB5	DB5 DB4 DI		DB2	DB1	DB0	Description	(fosc=270Khz)	
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "00H" to DDRAM and set DDRAM address to "00H" from AC	1.53ms	
Return Home	0	0	0	0	0	0	0	0	1	_	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.53ms	
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	SH	Assign cursor moving direction and enable the shift of entire display.	39ü₅	
Display ON/OFF Control	0	0	0	0	0	0	1	D	С	В	Set display (D), cursor (C), and blinking of cursor (B) on/off control bit.	39Üs	
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	_	_	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	39üs	
Function Set	0	0	0	0	1	DL	N	F	_	_	Set interface data length (DL:8-bit/4-bit), numbers of display line (N:2-line/1-line)and, display font type (F:5x11 dots/5x8 dots)	39Üs	
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	39üs	
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter.	39üs	
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0üs	
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	43Ӵs	
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	43Ӵs	

 \bullet "-": don't care

<u>12</u>.<u>Timing Characteristic</u> <u>s</u>

12.1 Write Operation

Writing data from MPU



Item	Symbol	Min	Тур	Max	Unit
Enable cycle time	T _C	1200	—	—	ns
Enable pulse width	T _{PW}	140		_	ns
Enable rise/fall time	T_R, T_F			25	ns
Address set-up time (RS, R/W to E)	t _{AS}	0			ns
Address hold time	t _{AH}	10			ns
Data set-up time	t _{DSW}	40			ns
Data hold time	t _H	10			ns

12.2 Read Operation

Reading data from ST7066U



Ta=25°C, VDD=5V

Item	Symbol	Min	Тур	Max	Unit
Enable cycle time	T _C	1200	_	_	ns
Enable pulse width (high level)	T _{PW}	140	_		ns
Enable rise/fall time	T _R ,T _F			25	ns
Address set-up time (RS, R/W to E)	t _{AS}	0	_	_	ns
Address hold time	t _{AH}	10	_	_	ns
Data delay time	t _{DDR}	_	_	100	ns
Data hold time	t _H	10	—	_	ns

13. .Initializing of LCM



4-Bit Ineterface



8-Bit Ineterface

<u>14</u>. <u>Reliability</u>

Content of Reliability Test (Normal temperature, -10°C~60°C)

	Environmental Test		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	70°C 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-20°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	60°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-10°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 40 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	40°C ,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -10°C 25°C 60°C 30min 5min 30min 1 cycle	-10°C/60°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude :1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5k Ω CS=100pF 1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

15. Backlight Information

Specification

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITION
Supply Current	ILED	45	50	60	mA	V=4.1V
Supply Voltage	V	4.0	4.1	4.3	V	_
Reverse Voltage	VR			8	V	
Luminous Intensity	IV	60	80	_	CD/M ²	ILED=50mA
Wave Length	ӳр	568	570	574	nm	ILED=50mA
Life Time	_	-	100000	-	Hr.	ILEDJb50mA
Color	Yellow Gre	een	1	1	<u> </u>	1

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

2.Drive from pin15,pin16



ill never get Vee output from pin15)

16. Inspection specification

NO	Item	Criterion	AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 	ot. 0.65
02	Black or white spots on LCD (display only)	 2.1 White and black spots on display b0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3m 	2.5
03	LCD black spots, white spots,	3.1 Round type : As following drawing $A^{\text{T}} = A^{\text{T}} Q \downarrow$ $\Phi = V^{\text{T}} \vee Q \downarrow$ $\Phi = V^{\text{T}} \vee Q \downarrow$ $\Phi = A^{\text{T}} \vee Q \downarrow$	2.5
	contamination (non-display)	3.2 Line type : $(As following drawing)$ W b > V Acceptable Q T W b > V Accept no dens L b > 0.02 < W b > 2 L b > 0.03 < W b > 2 0.05 < W As round type	<u>se</u> 2.5
		Size Φ Acceptable Q T $\Phi \downarrow \flat \checkmark \flat$ Accept no dense $\checkmark \lor \Diamond \downarrow \flat \checkmark \flat$ 3 $\checkmark \lor \Diamond \downarrow \flat \checkmark \flat$ 2	
		<i>м</i> ≫< ⊕ 0	
		Total Q TY 3	

04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	2.5
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NO	Item	Criterion	AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination	
06	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:	2.5



NO	Item	Criterion		
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5	
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 		
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.		
10	PCB \ COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	 2.5 2.5 0.65 2.5 0.65 0.65 2.5 2.5 2.5 	
		$\mathbf{Y} \xrightarrow{\mathbf{X}} \mathbf{X} * \mathbf{Y} \leq 2mm2$		
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65	

NO	Item	Criterion			
NO	Item General appearance	 Criterion 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging 	AQL 2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65		
		specification sheet.12.11 mension and structure must conform to product specification sheet.	0.65		

<u>17. Material List of Components for</u> <u>**RoHs**</u>

 WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2.Process for RoHS requirement :

- (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow : 250° C, 30 seconds Max. ;

Connector soldering wave or hand soldering $: 320^{\circ}$ C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : $235\pm5^{\circ}C$;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

Module		<u>LCM Sampl</u>			dba	ack	<u>Sheet</u> Page: 1		
1 · <u>Panel Specification</u> :									
1.	Panel Type :		P	ass		NG	÷ ,		
2.	View Directi	on:		ass		NG	j ,		
3.	Numbers of I	Dots:		ass			;		
4.	View Area:			ass			i ,		
5.	Active Area	:		ass			;		
6.	Operating Te	emperature :	P	ass		NG	;		
7.	Storage Tem	perature :		ass		NG	÷,		
8.	Others :								
2 · <u>M</u>	lechanical Sp	ecification :							
1.	PCB Size :		P	ass		NG	÷ ,		
2.	Frame Size :		P	ass		NG	й,		
3.	Materal of Fi	ame :	P	ass		NG	й,		
4.	Connector Pe	osition:	P	ass		NG	й,		
5.	Fix Hole Pos	ition:	P	ass		NG	;		
6.	Backlight Po	sition :		ass		NG	;		
7.	Thickness of	PCB :		ass		NG	й,		
8.	U	ame to PCB :		ass			,		
9.	Height of Mo	odule:		ass			,		
10.	Others :		P	ass		NG	й,		
3 \ <u>R</u>	<u>elative Hole S</u>	Size :							
1.	Pitch of Con	nector :		ass		NG	,		
2.	Hole size of (Connector :		ass		NG	,		
3.	Mounting Ho	le size :	P	ass		NG	· ,		
4.	Mounting Ho	le Type :	P	ass		NG	· ,		
5.	Others :			ass		NG	,		
4 \ <u>B</u> a	acklight Spec	ification :							
1. []]	B/L Type:			ass		NG	,		
2.	B/L Color:		P	ass		NG	,		
3.]	B/L Driving V	oltage (Referen	ce for	LED Type)	:		Pass I NG ,		
4.]	B/L Driving C	Current :	P	ass		NG	,		
5.	Brightness of	B/L:	P	ass		NG	,		
6.	B/L Solder Mo	ethod :	P	ass		NG	,		
7. (Others :		P	ass		NG	,		

>>~ Go to page 2 <<





Sales signature : _____ Customer Signature : _____

Date : / /